

**IN THE CLAIMS**

Please amend the claims as follows:

Claims 1-21. (Canceled)

22. (Currently Amended) A component package fabricated by:

depositing an underfill material over a plurality of pads in a component-mounting area of a substrate, the underfill material comprising a filler material containing particles;

placing a component on the component-mounting area, such that terminals of the component are aligned with corresponding pads and substantially enveloped in the underfill material, the particles potentially inhibiting a suitable connection between corresponding terminals and pads unless the particles are substantially removed; ~~[[and]]~~

applying suitable pressure to cause the terminals to physically contact the pads and to remove most but not all potentially inhibiting particles from between corresponding terminals and pads, with one or more particles being embedded in one of the terminals, in its corresponding pad, or in both the one terminal and its corresponding pad without preventing adequate physical and electrical contact; and

applying suitable heat to melt solder situated between the terminals and pads, which when cooled results in an electrical and mechanical connection between corresponding terminals and pads.

23. (Currently Amended) The component package recited in claim 22 ~~[[35]]~~ and fabricated such that the operations of applying suitable pressure and suitable heat are performed substantially concurrently by apparatus from the group comprising a thermocompression bonder, an ultrasonic bonder, and a component placement tool.

24. (Currently Amended) The component package recited in claim 22 ~~[[35]]~~ and fabricated such that the pads are pre-coated with solder, and wherein, in applying suitable heat, the terminals become attached to the pads through the solder.

25. (Currently Amended) The component package recited in claim 22 [[35]] and fabricated such that the terminals are pre-coated with solder, and wherein, in applying suitable heat, the terminals become attached to the pads through the solder.

26. (Previously Presented) The component package recited in claim 22, wherein the filler material is selected from the group consisting of silica, silicon oxide, silicon dioxide, silicon nitride, aluminum oxide, and aluminum nitride.

27. (Currently Amended) An electronic assembly comprising at least one integrated circuit (IC) package fabricated by:

depositing an underfill material over a plurality of pads in an IC mounting area of a substrate, the underfill material comprising a filler material containing particles;

placing an IC on the IC mounting area, such that terminals of the IC are aligned with corresponding pads and substantially enveloped in the underfill material, the particles potentially inhibiting a suitable connection between corresponding terminals and pads unless the particles are substantially removed; [[and]]

applying suitable pressure to cause the terminals to physically contact the pads and to squeeze out most but not all potentially inhibiting particles from between corresponding terminals and pads, with one or more particles being embedded in one of the terminals, in its corresponding pad, or in both the one terminal and its corresponding pad without preventing adequate physical and electrical contact; and

applying suitable heat to melt solder situated between the terminals and pads, which when cooled results in an electrical and mechanical connection between corresponding terminals and pads.

28. (Currently Amended) The electronic assembly recited in claim 27 [[36]] and fabricated such that the operations of applying suitable pressure and suitable heat are performed substantially concurrently by apparatus from the group comprising a thermocompression bonder, an ultrasonic bonder, and a component placement tool.

29. (Currently Amended) The electronic assembly recited in claim 27 [[36]], wherein the underfill material comprises a filler material selected from the group consisting of silica, silicon oxide, silicon dioxide, silicon nitride, aluminum oxide, and aluminum nitride.

Claims 30-45. (Canceled)

46. (Currently Amended) The component package recited in claim 22 [[35]], wherein the underfill material further comprises a fluxing agent, and wherein, in the operation of applying suitable heat, the fluxing agent cleans the terminals and the pads.

47. (Currently Amended) The electronic assembly recited in claim 27 [[36]], wherein the underfill material further comprises a fluxing agent, and wherein, in the operation of applying suitable heat, the fluxing agent cleans the terminals and the pads.

Claims 48-52. (Canceled)